

## Dual P-Channel 1.8 V (G-S) MOSFET

### PRODUCT SUMMARY

$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
- 8	0.070 at $V_{GS} = - 4.5$ V	- 4.6
	0.108 at $V_{GS} = - 2.5$ V	- 3.7
	0.162 at $V_{GS} = - 1.8$ V	- 3.0

### FEATURES

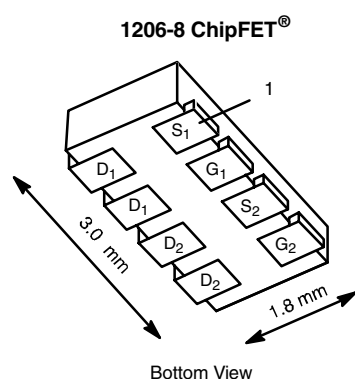
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Low Thermal Resistance
- 40 % Smaller Footprint than TSOP-6
- Compliant to RoHS Directive 2002/95/EC



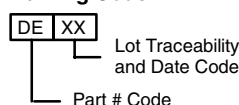
**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
Available

### APPLICATIONS

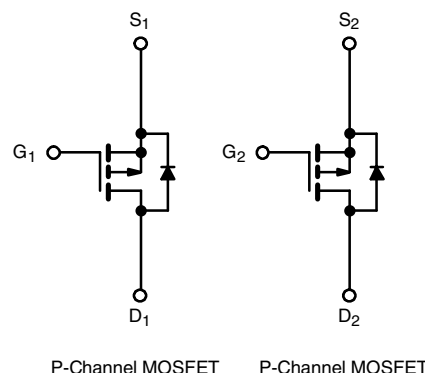
- Load Switch or PA Switch for Portable Devices



#### Marking Code



**Ordering Information:** Si5915DC-T1-E3 (Lead (Pb)-free)  
Si5915DC-T1-GE3 (Lead (Pb)-free and Halogen-free)



### ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$ , unless otherwise noted

Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		$V_{DS}$	- 8		V
Gate-Source Voltage		$V_{GS}$	$\pm$ 8		
Continuous Drain Current ( $T_J = 150\text{ }^{\circ}\text{C}$ ) <sup>a</sup>	$T_A = 25\text{ }^{\circ}\text{C}$	$I_D$	- 4.6	- 3.4	A
	$T_A = 85\text{ }^{\circ}\text{C}$		- 3.3	- 2.5	
Pulsed Drain Current		$I_{DM}$	- 10		
Continuous Source Current (Diode Conduction) <sup>a</sup>		$I_S$	- 1.8	- 0.9	
Maximum Power Dissipation <sup>a</sup>	$T_A = 25\text{ }^{\circ}\text{C}$	$P_D$	2.1	1.1	W
	$T_A = 85\text{ }^{\circ}\text{C}$		1.1	0.6	
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	- 55 to 150		$^{\circ}\text{C}$
Soldering Recommendations (Peak Temperature) <sup>b, c</sup>			260		

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	$R_{thJA}$	50	60	$^\circ\text{C/W}$
		90	110	
Maximum Junction-to-Foot (Drain)	$R_{thJF}$	30	40	

Notes:

- Surface mounted on 1" x 1" FR4 board.
- See reliability manual for profile. The ChipFET is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

**SPECIFICATIONS**  $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted

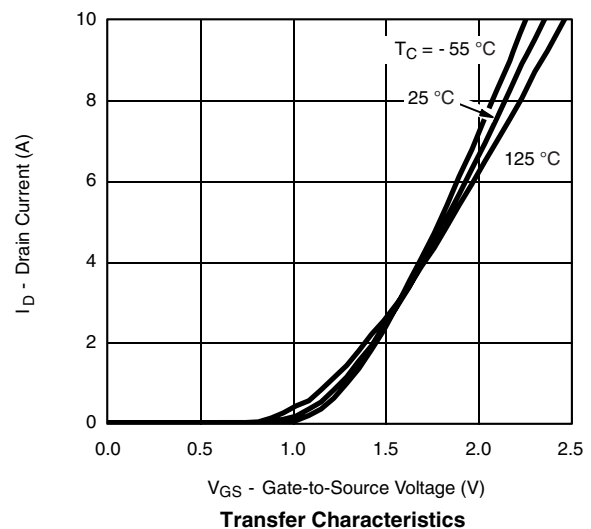
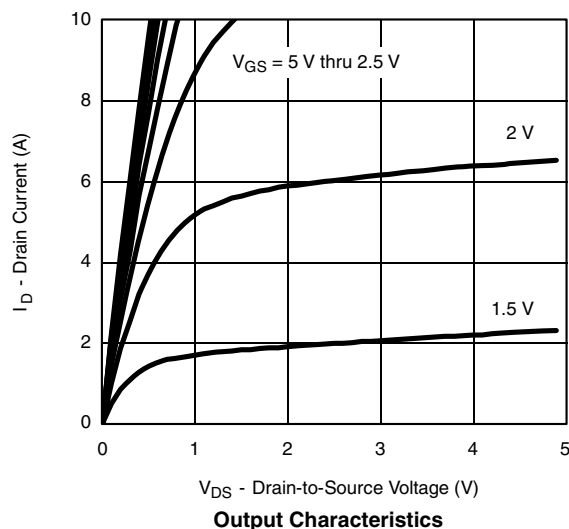
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -250\text{ }\mu\text{A}$	-0.45			V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 8\text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -6.4\text{ V}$ , $V_{GS} = 0\text{ V}$			-1	$\mu\text{A}$
		$V_{DS} = -6.4\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 85\text{ }^{\circ}\text{C}$			-5	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \leq -5\text{ V}$ , $V_{GS} = -4.5\text{ V}$	-10			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = -4.5\text{ V}$ , $I_D = -3.4\text{ A}$		0.058	0.070	$\Omega$
		$V_{GS} = -2.5\text{ V}$ , $I_D = -2.7\text{ A}$		0.090	0.108	
		$V_{GS} = -1.8\text{ V}$ , $I_D = -1\text{ A}$		0.131	0.162	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = -5\text{ V}$ , $I_D = -3.4\text{ A}$		8		S
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = -0.9\text{ A}$ , $V_{GS} = 0\text{ V}$		-0.8	-1.2	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = -4\text{ V}$ , $V_{GS} = -4.5\text{ V}$ , $I_D = -3.4\text{ A}$		5.9	9	nC
Gate-Source Charge	$Q_{gs}$			1.3		
Gate-Drain Charge	$Q_{gd}$			1.4		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -4\text{ V}$ , $R_L = 4\text{ }\Omega$ $I_D \cong -1\text{ A}$ , $V_{GEN} = -4.5\text{ V}$ , $R_g = 6\text{ }\Omega$		20	30	ns
Rise Time	$t_r$			70	110	
Turn-Off Delay Time	$t_{d(off)}$			35	55	
Fall Time	$t_f$			35	55	
Source-Drain Reverse Recovery Time	$t_{rr}$			30	60	

Notes:

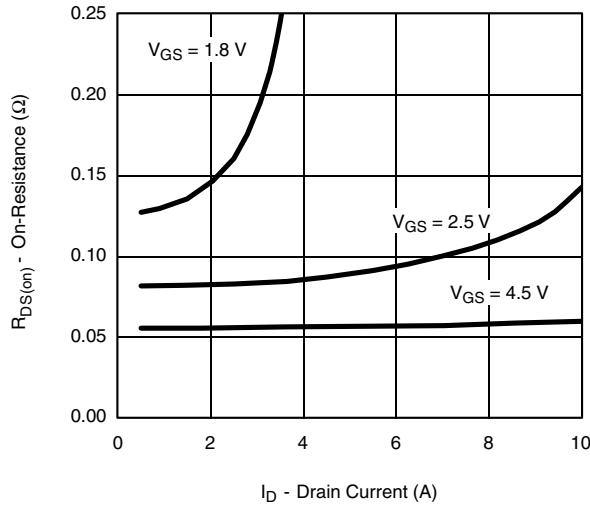
a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .

b. Guaranteed by design, not subject to production testing.

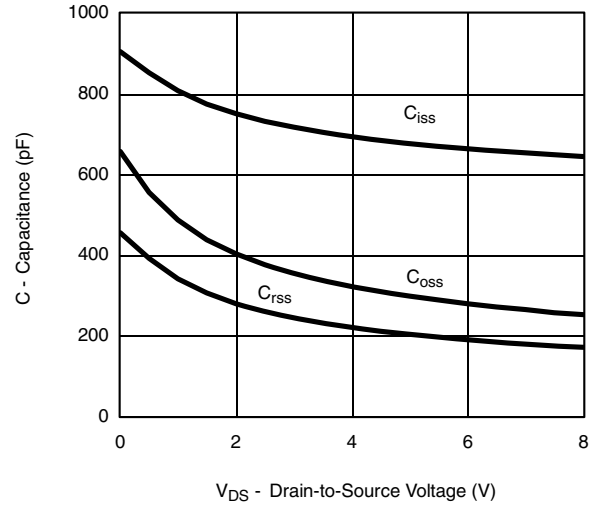
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS**  $25\text{ }^{\circ}\text{C}$ , unless otherwise noted

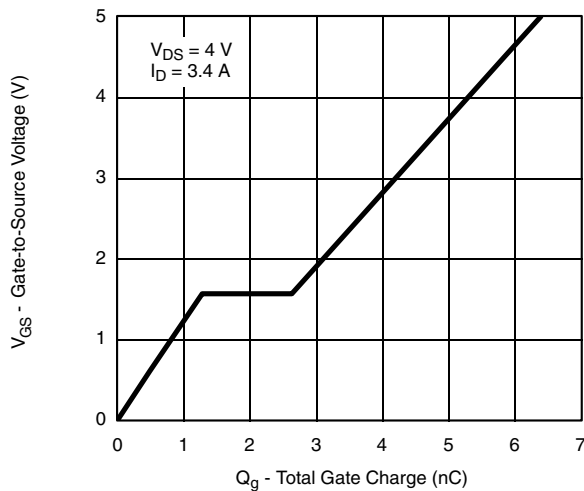
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



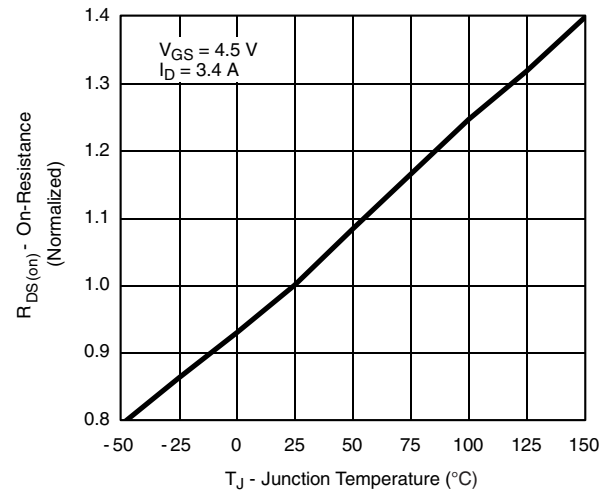
On-Resistance vs. Drain Current



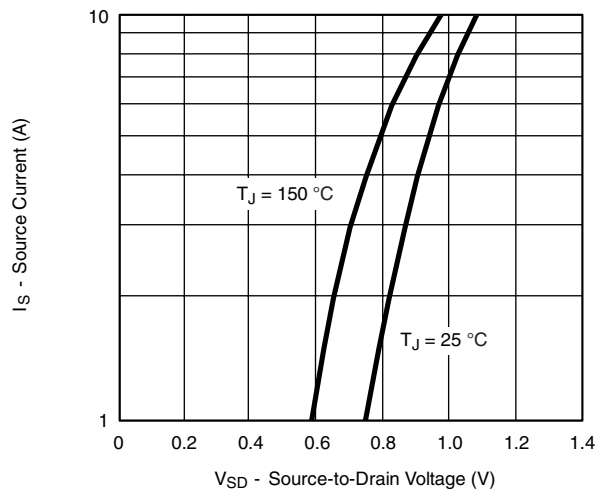
Capacitance



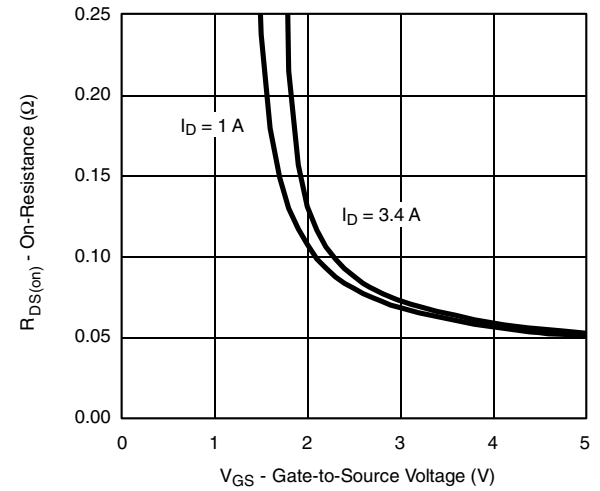
Gate Charge



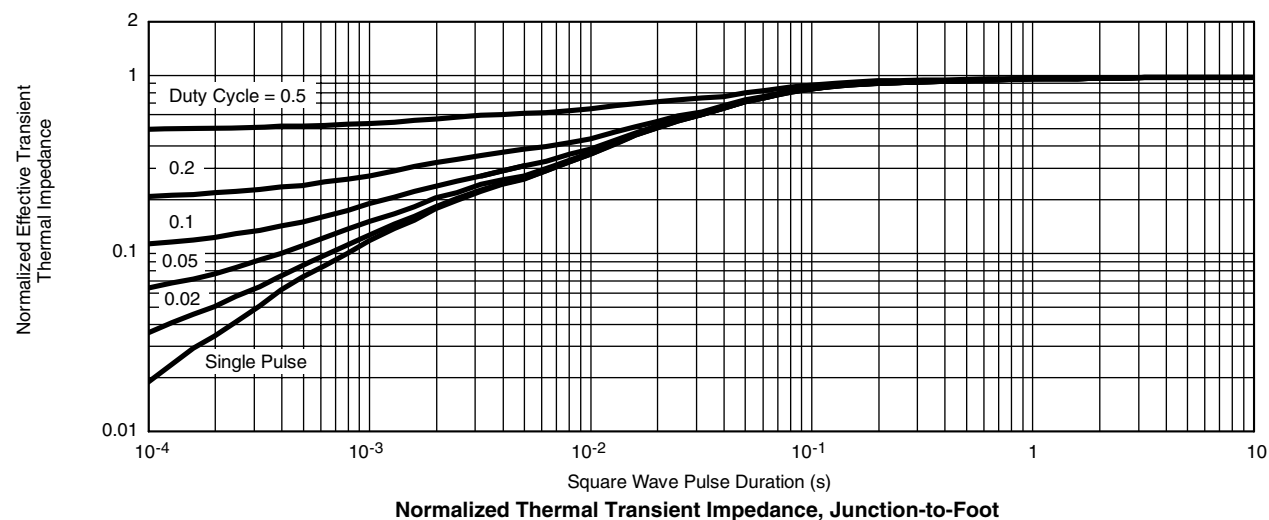
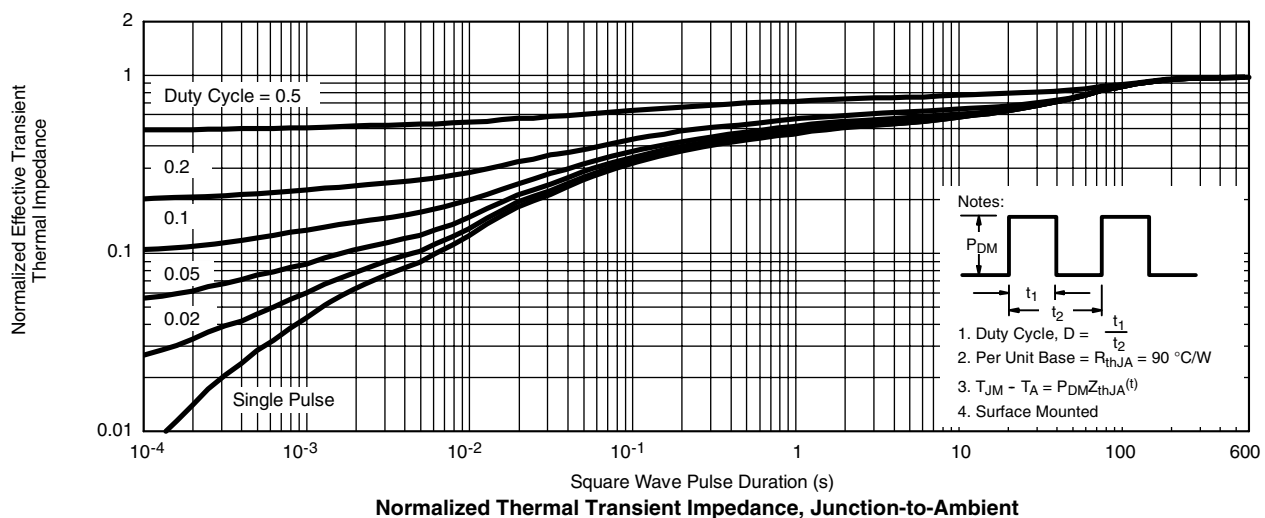
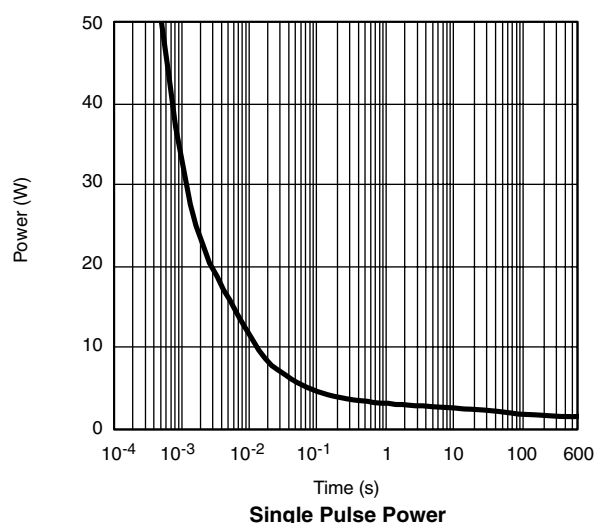
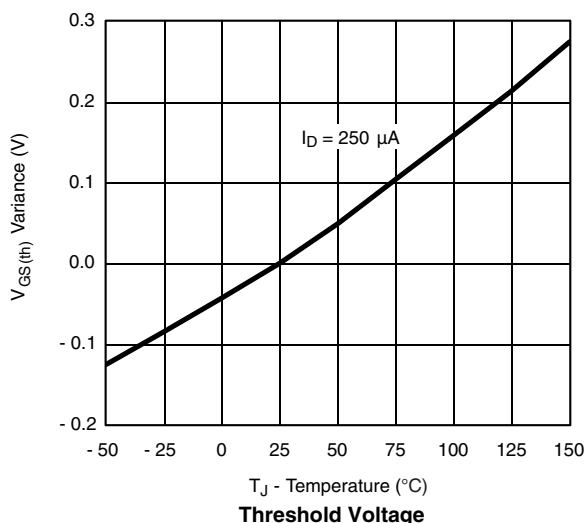
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

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